

## Supporting Information

### Preparation of cyclotriphosphazene microsphere bearing phosphaphenanthrene structure towards fire-safety and mechanic-enhancement for epoxy and its aramid fiber composite

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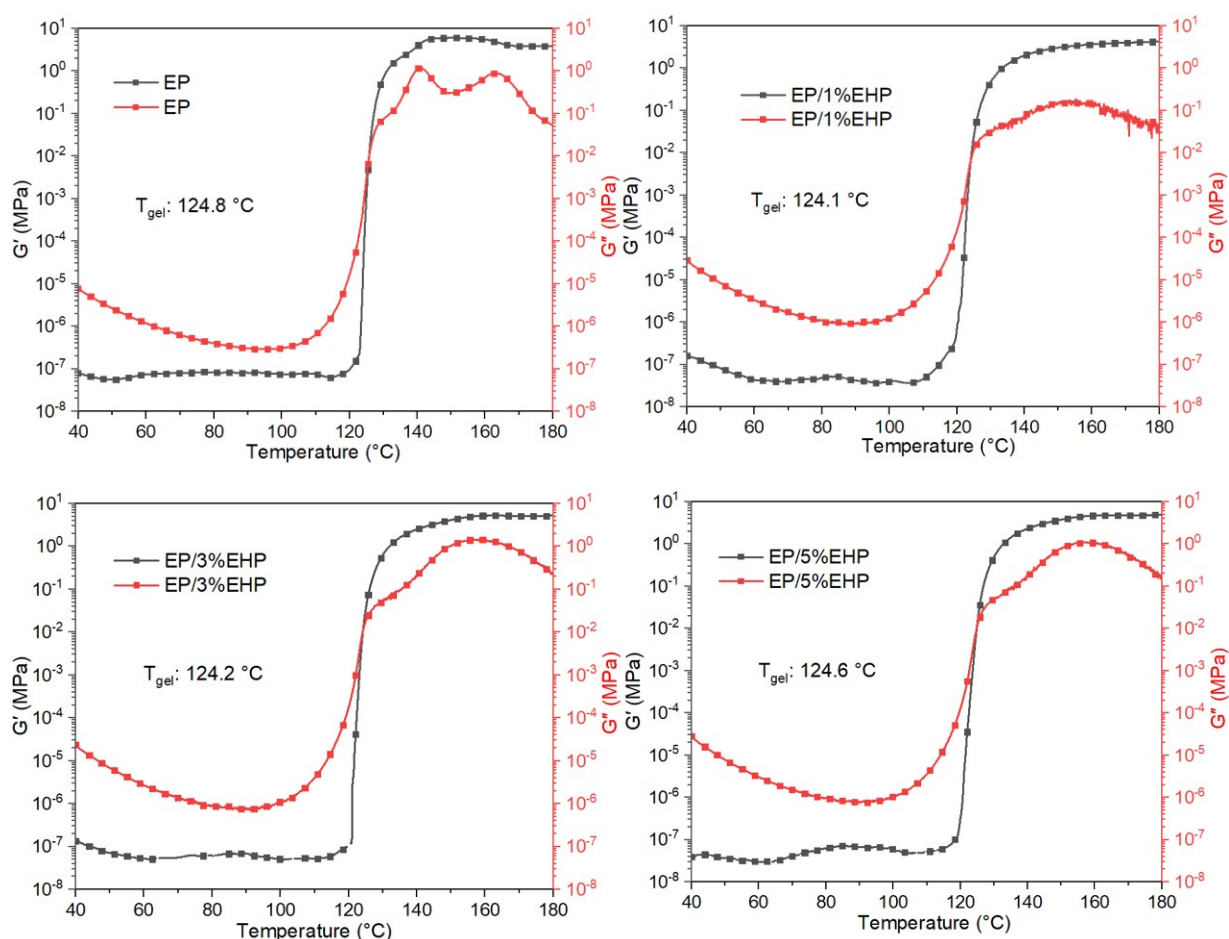


Figure S1 Rheology curves of modulus vs temperature for epoxy resins